



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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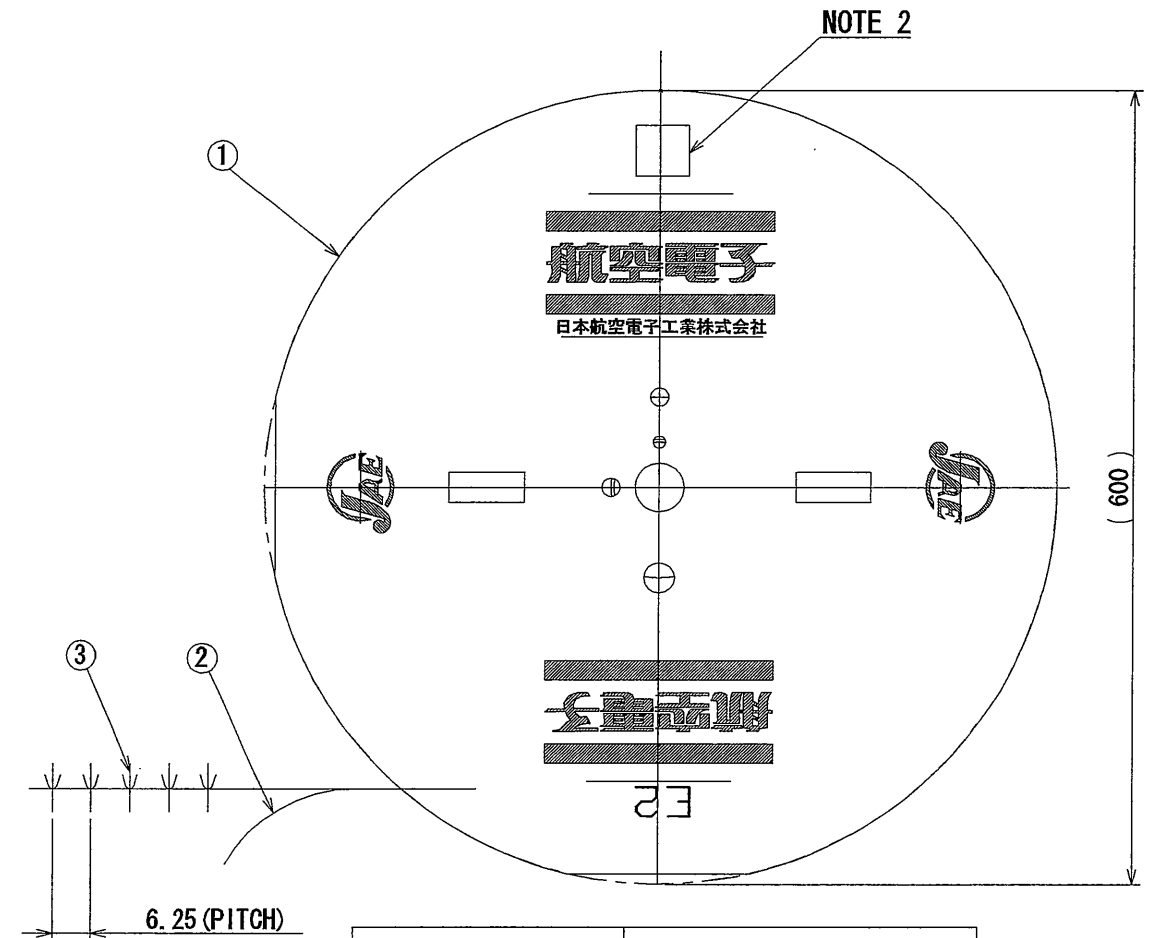
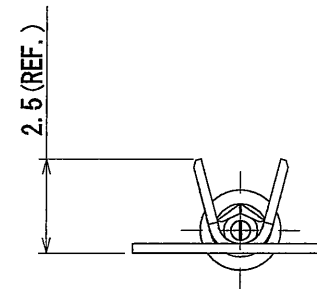
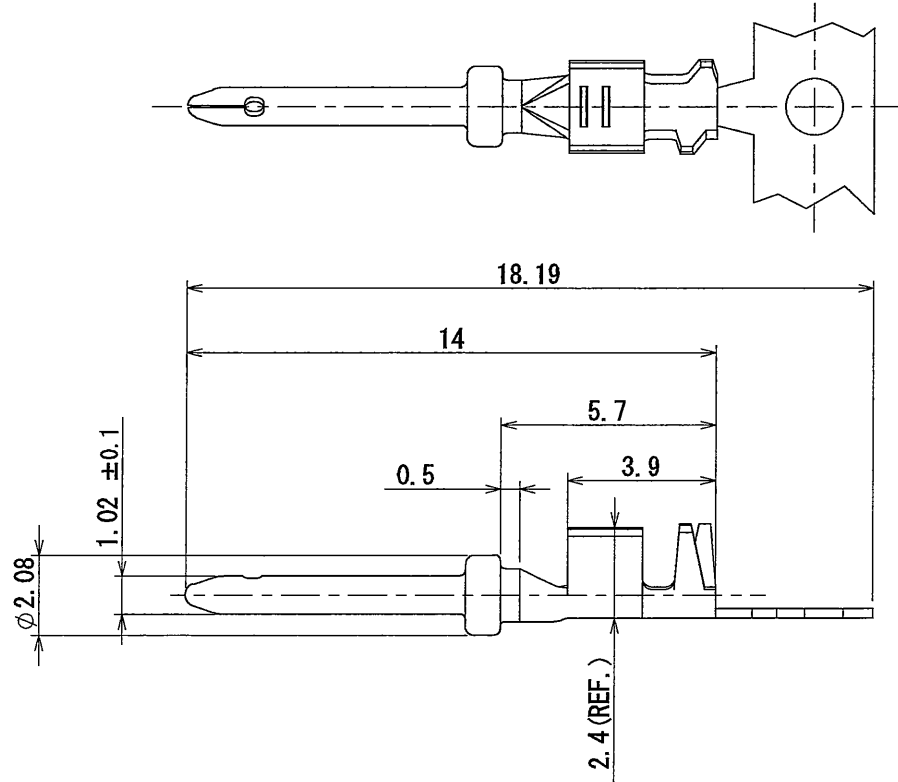
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SJ017494

(DRAWING NO.) (台票圖号)

版数 REV.	年月日 DATE	DCN No.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
3	12/Nov/2010	071025	Japanese→Bilingual ラベル貼り付け位置変更 他	M. SHINOZAKI	K. KUGOU	O. TAKAGI	Y. OTSUKA



NOTE 2

- NOTE 1. CONTACTS ARE SUPPLIED IN REELED FROM WITH 10000 CONTACTD PER REEL.
 2. MARK TRADE PART No. AND No. OF CONTACTS.
 3. CRIMP TOOL
 TYPE: CT350-2B-D*C (D*C SEMI AUTOMATIC CRIMPING MACHINE)
 4. RELATION BETWEEN INSULATION DIA. AND EXTRACTION TOOL.

INSULATION DIA	EXTRACTION TOOL	REMARK
φ 1.2~1.7	JJET-D*C-20 (MADE OF PLASTIC)	—
φ 1.2~1.95	ET-20D (MADE OF METAL)	—
φ 1.96 OR MORE	JJET-D*C-20 OR ET-20D	WHEN EXTRACTED WIRE HAS TO BE CUT

NOTE 5. CONTACT FINISH

MATING PORTION	GOLD 0.1 μM (MIN.) OVER NICKEL
OTHER AREA	GOLD FLASH

PART No. 名称	D*C-20-18P-10000
使用電線 WIRE ACCOMMODATION	AWG#18~#22 (仕上外径: 注4) (INSULATION DIA: SEE NOTE4)

注 5. コンタクト仕上

接触部	Ni上Auメッキ (Au: 0.1 μm以上)
その他	Auフラッシュ

- 注1. 本コンタクトは、リール状で供給され、10000本/リールとする。
 2. 図示の位置に品名及び数量を記入した、ラベルが貼られている。
 3. 下記の半自動圧着機に装着する。
 型式: CT350-2B-D*C (D*C半自動圧着機)
 4. 電線仕上外径と引抜工具

適用仕上外径	引抜工具	備考
φ 1.2~φ 1.7	JJET-D*C-20 (プラスチック製)	—
φ 1.2~φ 1.95	ET-20D (金属製)	—
φ 1.96以上の場合	JJET-D*C-20 OR ET-20D	引抜場合は電線を切断しなければならない。

3	PIN CONTACT	10000	COPPER ALLOY	NOTE 5	—
2	TAPE	1	PAPER	—	—
1	MAGAZINE	1	PAPER	—	—

仕様書 (SPECIFICATION)	第1版 (ORIGINAL DATE)	尺度 (SCALE)	シリーズ (SERIES)	備考 (REMARKS)
一般公差 (GENERAL TOLERANCE)	28/Jul/1983		Dsub	
寸法 (DIMENSION)	製図 DR.	名称 (TITLE)	日本航空電子工業株式会社	
角度 (ANGLES)	担当 CHK.	D*C-20-18P-10000	JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.	
±	査閲 APPD.		図面番号 (DRAWING NO.)	
× ± 0.4	承認 APPD.		SJ017494	
×× ± 0.2		質量 (MASS)	版数 (REV.)	
××× ±			3	

DCF-C-212F (05.08)

